



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



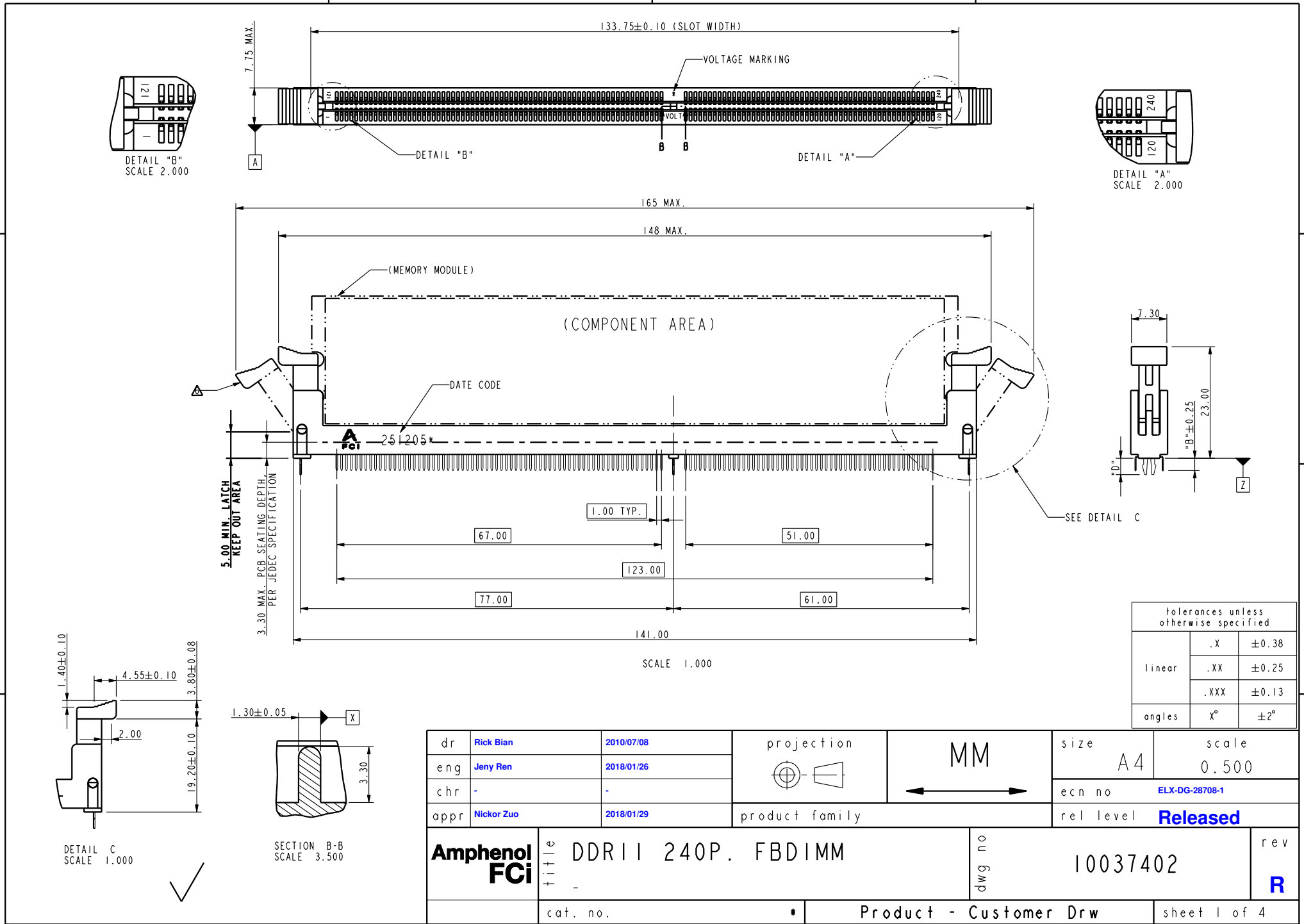
Contact us

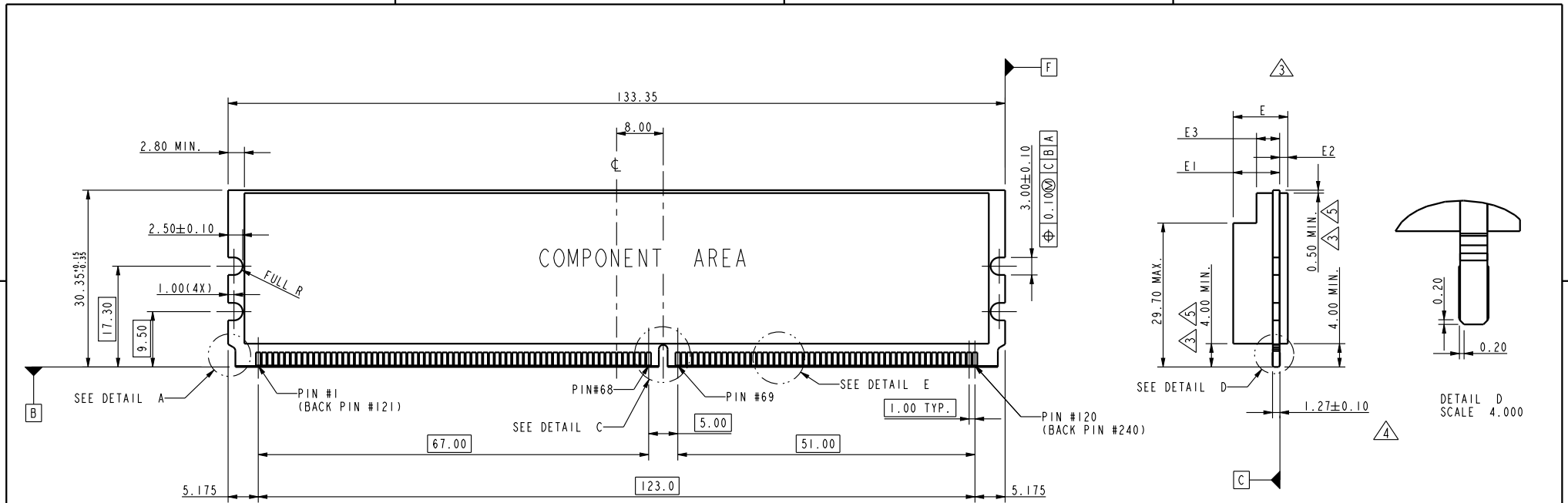
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

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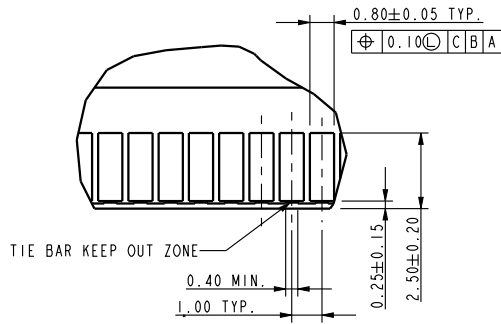
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



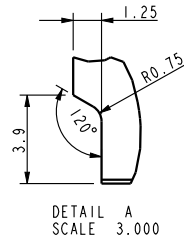




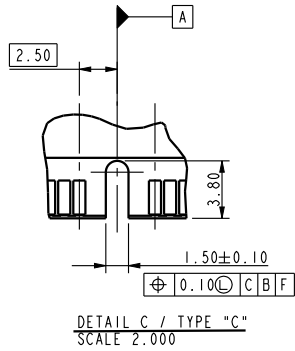
SCALE 1.000
RECOMMENDED MODULE LAYOUT (PER JEDEC MO-256)



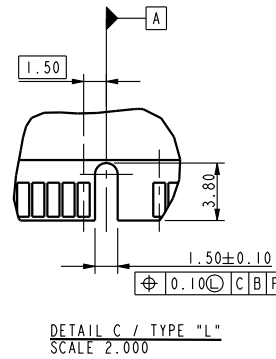
DETAIL E
SCALE 4.000



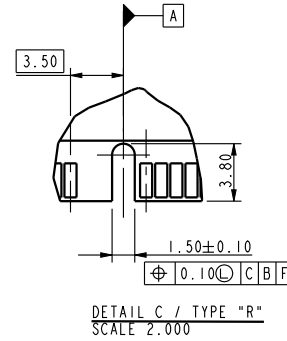
DETAIL A
SCALE 3.000



DETAIL C / TYPE "C"
SCALE 2.000



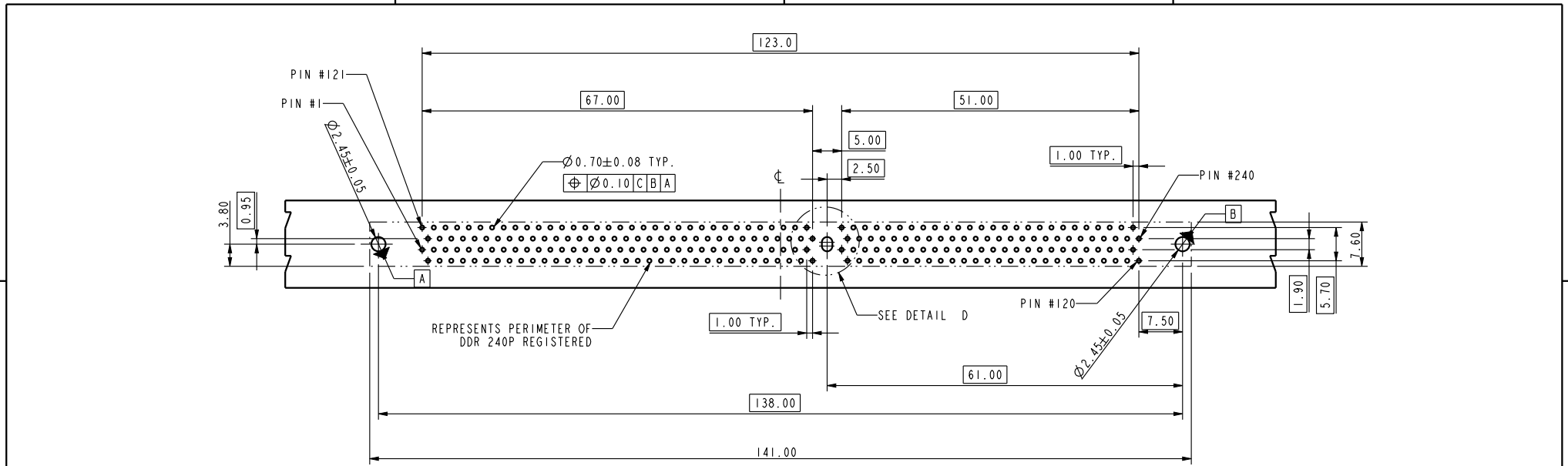
DETAIL C / TYPE "L"
SCALE 2.000



DETAIL C / TYPE "R"
SCALE 2.000

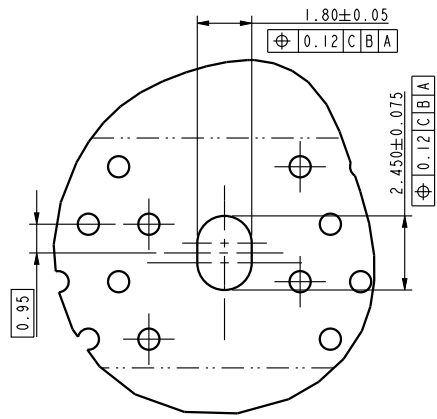
tolerances unless otherwise specified		
linear	.X	±0.38
	.XX	±0.15
	.XXX	±0.13
angles	x°	±2°

dr	Rick Bian	2010/07/08	projection 	MM 	size	A4	scale	0.500	
eng	Jeny Ren	2018/01/26			ecn no	ELX-DG-28708-1			
chr	-	-			rel level	Released			
appr	Nickor Zuo	2018/01/29	product family		rev	10037402		R	
Amphenol FCI		title			DDR11 240P. FBDIMM		cat. no.		* Product - Customer Drw
					dwg no		sheet 2 of 4		

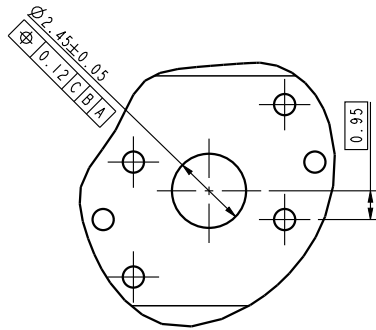


RECOMMENDED CIRCUIT BOARD HOLE LAYOUT
SCALE 1.000

DETAIL D
SCALE 4.000



OPTION 2
CENTER SLOT



OPTION 1
CENTER ROUND HOLE

SUB KEY POS. #1	DESCRIPTION	TYPE 1				TYPE 2			
		DIM. E1 MAX.	DIM. E2 MAX.	DIM. E3 MAX.	DIM. E MAX.	DIM. E1 MAX.	DIM. E2 MAX.	DIM. E3 MAX.	DIM. E MAX.
TYPE R	X.X VOTAGLE	6.80	1.40	2.80	8.20	6.80	3.00	4.40	9.80
TYPE L	2.5 VOLTAGE	6.80	1.40	2.80	8.20	6.80	3.00	4.40	9.80
TYPE C	1.8 VOLTAGE	6.80	1.40	2.80	8.20	6.80	3.00	4.40	9.80

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appr	Nickor Zuo	2018/01/29	product family			rev	R	
Amphenol FCI		title		DDR II 240P. FBDIMM		dwg no		10037402
cat. no.		*		Product - Customer Drw		sheet		3 of 4

10037402-□ □ □ □ □

STYLE : MECHANICAL KEYING

- 1 : 1.8 VOLT. W/TYPE "C"
- 2 : 2.5 VOLT. W/TYPE "L"
- 3 : X.X VOLT. W/TYPE "R"

**METAL CLIP
(WITH NI 1.27 um MIN. PLATING)**

- 1 : WITH METAL CLIP + DIM."D"=3.05
- 2 : WITH METAL CLIP + DIM."D"=3.56
- 3 : WITH METAL CLIP + DIM."D"=3.43

TAIL LENGTH

CODE	DIM. "B"	PCB THICKNESS
0	2.54	1.47 mm (0.058")
1	2.67	1.60 mm (0.063")
2	3.18	2.36 mm (0.093")
3	4.00	3.18 mm (0.125")

PLATING

CODE	CONTACT	SOLDERTAIL	UNDERPLATE
2	15 u"(0.38um) MIN. GOLD	100u"(2.54um) MIN. TIN/LEAD	50u"(1.27um) MIN. NICKEL OVERALL
3	30u"(0.76um) MIN. GOLD		
4	3u"(0.076um) MIN. GOLD		
7LF	15u"(0.38um) MIN. GOLD	100u"(2.54um) MIN. 100% TIN	50u"(1.27um) MIN. NICKEL OVERALL
8LF	30u"(0.76um) MIN. GOLD		
9LF	3u"(0.076um) MIN. GOLD		
2N	15 u"(0.38um) MIN. GOLD	100u"(2.54um) MIN. TIN/LEAD	90u"(2.29um) MIN. NICKEL OVERALL
3N	30 u"(0.76um) MIN. GOLD		
4N	3 u"(0.076um) MIN. GOLD		
7NLF	15 u"(0.38um) MIN. GOLD	100u"(2.54um) MIN. 100% TIN	90u"(2.29um) MIN. NICKEL OVERALL
8NLF	30 u"(0.76um) MIN. GOLD		
9NLF	3 u"(0.076um) MIN. GOLD		

COLOR OF HOUSING AND EJECTOR

- 0 : BLACK HOUSING + IVORY EJECTOR
- 1 : BLUE HOUSING + IVORY EJECTOR
- 2 : BLACK HOUSING + BLACK EJECTOR
- 3 : IVORY HOUSING + IVORY EJECTOR

NOTE:

1. MATERIAL:
HOUSING: HIGH PERFORMANCE RESINS, GLASS FILLED UL94V-0 RATED.
EJECTOR: HIGH PERFORMANCE RESINS, GLASS FILLED UL 94V-0 RATED.
TERMINAL : COPPER ALLOY.
METAL CLIP: COPPER ALLOY.
2. PRODUCT SPECIFICATION: GS-12-300.
DIMENSIONS APPLICABLE WHEN COMPONENTS MOUNTED ON ONE OR BOTH SIDES.
CARD THICKNESS APPLIES ACROSS TABS AND INCLUDES PLATING AND/OR
REALIZATION STRAIGHTNESS CALLOUT APPLIES TO ZONE DEFINED BY THE 4.00 CONTACT
AREA DIMENSION FOR THE ENTIRE LENGTH OF 133.35.
BOARD OF COMPONENT AREA.
3. LATCH DESIGN INCLUDES COMPLEMENTARY FEATURE TO ACCOMMODATE MODULE
END NOTCHES AS DEFINED IN DETAIL A OF P.2 AND AS SPECIFIED IN MO-256.
7. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS
AS DESCRIBED IN GS-22-008.
8. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMP. FOR 10 SECONDS IN A WAVE
SOLDER APPLICATION
9. 10037402-XXXXX(X)LF SERIES ARE FOR LEAD-FREE OPTIONS.
10. DATE CODE:XXXXXX* SHOWS DAY/MONTH/YEAR."*" MEANS PRODUCTION LINE CODE.



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